

Highlights

- Manufactured exclusively with 100 % natural DeBeers diamonds
- Available in outer diameters ranging from 8" up to 34"
- Custom-made blades available upon request

Electronically plated annealed nickel, with diamond abrasive

ID Slicing Blades

Semiconductor Materials, Inc (SMI) patented multi-layered diamond ID slicing blades are specifically designed and manufactured to maximize wafer yields in all types of semiconductor materials. The SMI ID Blade and its high-speed, creep-resistant core materials are specifically manufactured for all higher tensioning, minimizing blade bow, saw marks, and exit chipping.

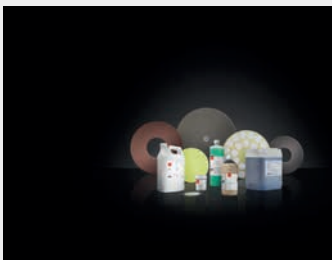
The Mark III line of ID blades has been designed specifically for slicing silicon ingots, while Mark V is ideal for harder materials such as quartz, sapphire, magnets, and ceramics.

Typical applications

Ceramic, sapphire, silicon, quartz



ID Slicing blades are made with natural diamonds to minimize wafer surface and substrate damage.



Pureon offers a wide range of customized solutions. Get in touch with us.

Product specifications

Base material Stainless steel
Shelf life None

Order information

Packing SMI ID Blades are packaged in customized flat boxes, which may contain 1 – 25 pieces.

Application recommendations

Handling It is crucial that the ID blade be installed correctly to ensure proper cutting performance. It is important to clean all surfaces, discard old bolts and screws, and properly align the blade using the locating pins. New bolts should be torqued to 250 in-lbs. Please contact your local Pureon representative for additional information and instructions.

Disposal Dispose of in accordance with all applicable local regulations.

Pureon is an Authorized distributor of Semiconductor Materials, Inc.

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